VCC | OPTOELECTRONICS
lighting:theway

PLCC2 SMD TYPE LED

VAOL-S2GT4

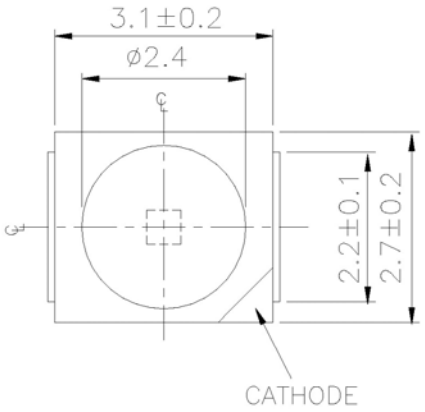
Features

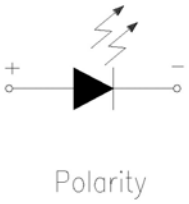
- Fit automatic placement equipment.
- Fit Compatible with vapor-phase reflow, Infrared reflow and wave solder processes.
- White package.
- Pb-free.
- RoHS compliant.

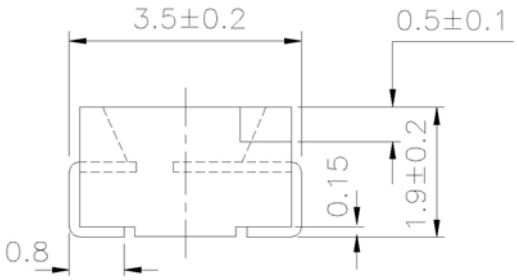
Descriptions

- For higher packing density .
- For minature applications .
- Water clear lens .
- Chip material : AlGaInP .
- Emitting color : Yellow Green .

Package Outline Dimensions

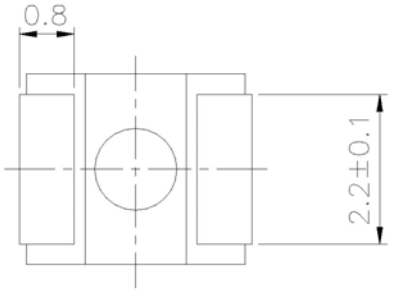


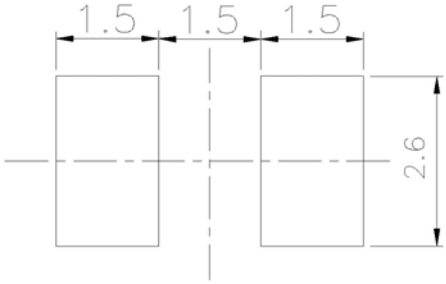






For reflow soldering (Proposal)





Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

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RoHS
ISO 9001 Registered

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	50	mA
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Electrostatic Discharge(HBM)	ESD	2000	V
Power Dissipation	Pd	100	mW
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	80	mA
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	*Chip Rank	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_V	E2	25	37	-----	mcd	I_F=20mA
		E3	32	51			
		E4	40	70			
		E5	50	96			
Viewing Angle	2θ 1/2	-----	-----	120	-----	deg	I_F=20mA
Peak Wavelength	λ p	-----	-----	575	-----	nm	I_F=20mA
Dominant Wavelength	λ d	-----	-----	573	-----	nm	I_F=20mA
Spectrum Radiation Bandwidth	$\triangle\lambda$	-----	-----	20	-----	nm	I_F=20mA
Forward Voltage	V_F	-----	-----	2.0	2.4	V	I_F=20mA
Reverse Current	I_R	-----	-----	-----	10	μA	V_R=5V

Specific binning requirements- please contact our home office

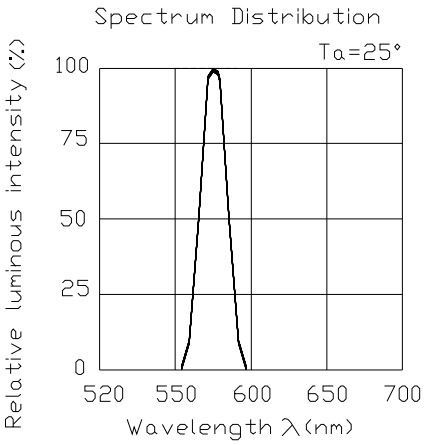
Notes:

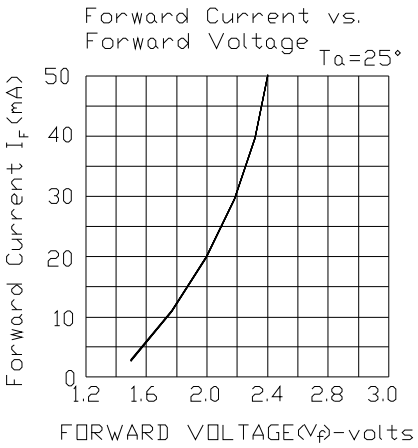
1.Tolerance of Luminous Intensity ±10%

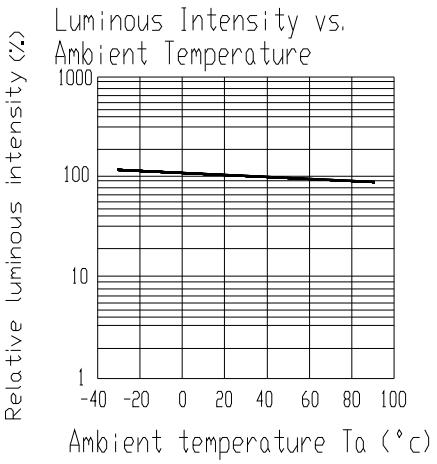
2.Tolerance of Dominant Wavelength ± 1nm

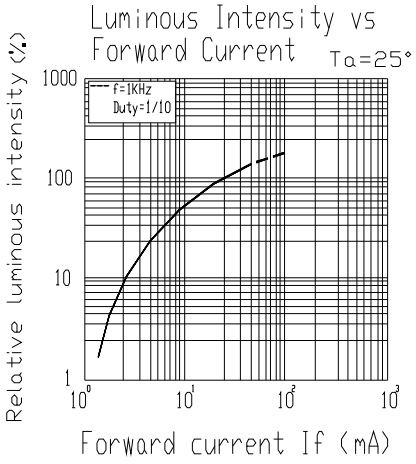
3.Tolerance of Forward Voltage ±0.1V

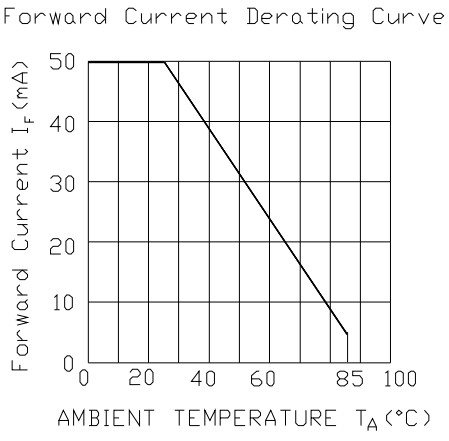
Typical Electro-Optical Characteristics Curves

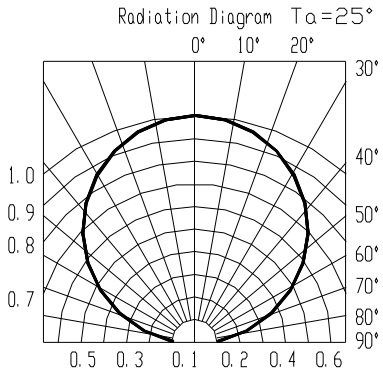




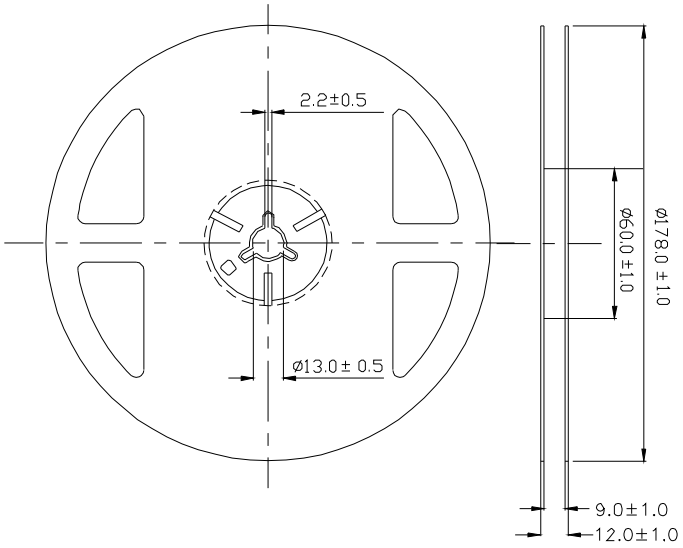






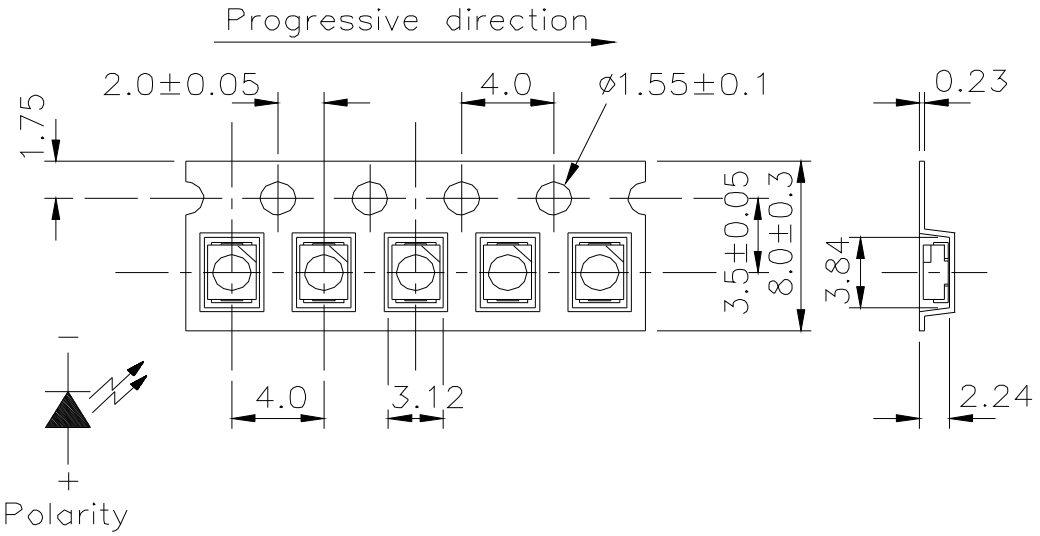


Reel Dimensions



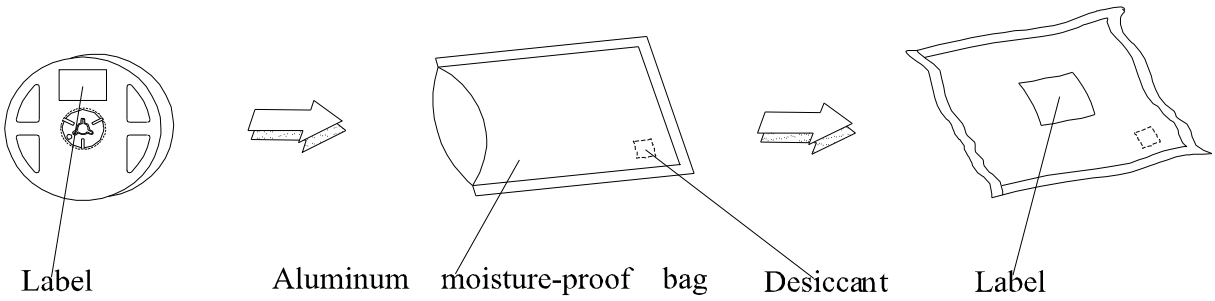
Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.



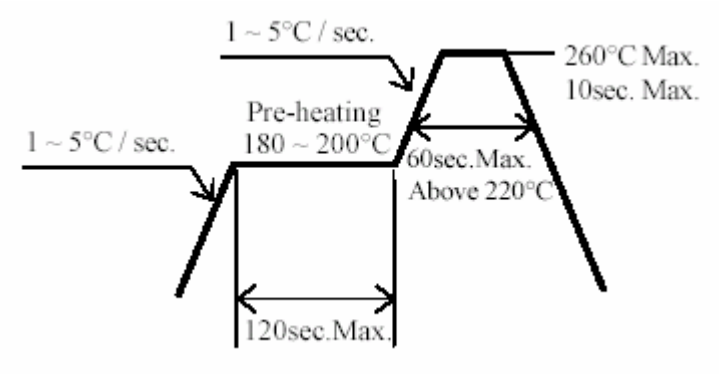
Note: The tolerances unless mentioned is ±0.1mm Unit = mm

Moisture Resistant Packaging



Soldering Condition

1.Pb-free solder temperature profile



2.Reflow soldering should not be done more than two times.

3 When soldering, do not put stress on the LEDs during heating.

4 After soldering, do not warp the circuit board.

Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.